# DIE BONDER

# **T-3002-PRC**

The T-3002-PRO series is Tresky's most flexible die bonding platform. The True Vertical Technology<sup>Th</sup> systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the PRO incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any Ultra precise bond-height control bond height. Together with superior ergonomics the PRO platform is the industry's most sophisticated system in its class and with the new PC software even easier Unique pick-up from wafer to operate.

The T-3002-PRO is equiped with Tresky's die ejector system for pick-up from wafer.





Switzerland

Email: tresky@tresky.com

www.tresky.com

PRELIMINARY

Full PC-Control

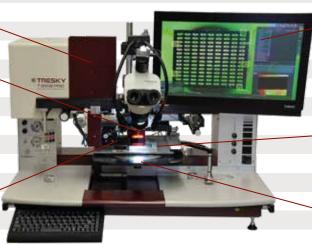
Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bonding force control.

#### **APPLICATIONS:**

Die Attach, Die Sorting, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn, .....), ......

# FEATURES AND OPTIONS:

- Programmable Z-Drive with Bonding Force Control
- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub,Tool Heating, Pre Form Spindle, ...
- Flip-Chip Ultra Beam Splitter with multi point alignment
  » 1µm placement accuracy



Interface for all bonding parameter, temperature profile and video imaging of Beam Splitter Optics, Process Inspection Camera

XY placement stage supporting: -Waffle/Gel - Pack -, Substrate -Holder, various Heating Plates

Pick-up from Wafer with Tresky's – patented die ejector system, especialy suitable for all kind of Si, GaAs and InP dies down to 30µm thickness

# TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g (other force ranges available)
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	±10µm; ±1µm optional (process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V
	Note: All specifications are subject to change without notice

## **REPRESENTED BY:**

## HEADQUATERS

#### Dr. TRESKY AG

Boehnirainstr. 13 CH-8800 Thalwil Switzerland Tel.: +41 44 772 1941 Fax: +41 44 772 1945 tresky@tresky.com

#### TRESKY Corporation

704 Ginesi Drive, Suite 11A Morganville, NJ 07751 USA

Tel.: +1 732 536 8600 Fax: +1 732 536 0495 sales@tresky.com



www.tresky.com

